[0007]

There is provided an adhesive agent comprising a polyimide (a), an epoxy compound (b), and an acid-modified rosin (c).

[0007a]

In a first aspect, there is provided an adhesive agent comprising a polyimide (a), an epoxy compound (b), an acid-modified rosin (c) and a basic latent hardener, wherein the acid modified rosin (c) has a cyclohexane ring.

[0007b]

In a second aspect, there is provided an adhesive agent film comprising the adhesive agent as defined above.

[0007c]

In a third aspect, there is provided a semiconductor device including a hardened article of the adhesive agent as defined above or a hardened article of the adhesive agent film as defined above.

[0007d]

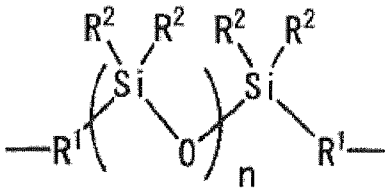
In a fourth aspect, there is provided a method for producing a semiconductor device, wherein the adhesive agent as defined above or the adhesive agent film as defined above is interposed between a first circuit member and a second circuit member; and the first circuit member and the second circuit member are electrically connected to each other through application of heat and pressure.

CLAIMS

1. An adhesive agent comprising a polyimide (a), an epoxy compound (b), an acid-modified rosin (c), and a basic latent hardener, wherein the acid modified rosin (c) has a cyclohexane ring.

2. The adhesive agent according to claim 1, wherein the polyimide (a) is a polymer having a structure represented by a general formula (2) or a general formula (3) and containing a structure represented by a general formula (1) as R^4 in the general formula (2) or the general formula (3) in an amount of 5 to 15% by mass with respect to the total amount of the polymer:

[Chem. 1]



(1)

in which R^1s represent a divalent hydrocarbon group, and may be the same or different in one molecule and may be the same or different in different molecules , R^2s represent a monovalent hydrocarbon group, and may be the same or different in one molecule and may be the same or different in different molecules, and n is an integer of 1 to 10;

[Chem. 2]